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Part Number: [0432028926](#)
Status: **Active**
Overview: [modular_plugs_jacks](#)
Description: Modular Jack, Right Angle, Low Profile, Shielded, Offset Panel Grounding Tabs, with Bottom Grounding Tab, Rear Position PCB Ground Tab, 8/8

Documents:

[3D Model](#) [Product Specification PS-43202-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E107635

General

Product Family Modular Jacks/Plugs
 Series [43202](#)
 Comments Enhanced panel grounding tabs
 Component Type PCB Jack
 Magnetic No
 Overview [modular_plugs_jacks](#)
 Performance Category 3
 Power over Ethernet (PoE) N/A
 Product Name RJ45

Physical

Color - Resin Black
 Durability (mating cycles max) 500
 Flammability 94V-0
 Inverted / Top Latch No
 Lightpipes/LEDs None
 Material - Metal Brass, Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Orientation Right Angle (Side Entry)
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.60 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.050 In
 Pitch - Mating Interface (mm) 1.27 mm
 Plating min: Mating (µin) 50
 Plating min: Mating (µm) 1.25
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.5
 Ports 1
 Positions / Loaded Contacts 8/8
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -40°C to +85°C
 Termination Interface: Style Through Hole
 Wire/Cable Type N/A

Electrical

Current - Maximum per Contact 1.5A
 Grounding to PCB Yes



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Halogen-Free
 Status**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[43202Series](#)

Mates With

FCC 68 Plugs

Grounding to Panel
Shielded
Voltage - Maximum

Offset Panel Ground Tabs
Yes
125V

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
Lead-free Process Capability Wave Capable (TH only)
Max. Cycles at Max. Process Temperature 1
Process Temperature max. C 260

Material Info

Reference - Drawing Numbers

Packaging Specification PK-43202-004
Product Specification PS-43202-001, RPS-43202-002
Sales Drawing SDA-43202

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SHIELDED MODULAR JACK SHOWN WITH PANEL GROUND OPTION 'D' AND FRONT PCB GROUND TABS.

NOTES:

- 1) MATERIAL:
 HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
 INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
 TERMINALS: PHOSPHOR BRONZE, .012/ 0.30 THICK
 SHIELD: BRASS, .007/ 0.18 THICK
- 2) FINISH:
 TERMINALS:
 A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
 B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
 *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
 CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
- SHIELD:
 100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27 MICROMETERS COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43202.
- 4) PACKAGING SPECIFICATION:
 UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43202-003.
 UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES PER MOLEX PACKAGING SPECIFICATION PK-43202-005.
 SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43202-004.
- 5) SEE SHEETS 7 - 9 FOR P.C. BOARD LAYOUTS.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

9	L2
8	L2
7	L2
6	L4
5	L
4	K2
3	L1
2	L1
1	L4
SH	REV

DRAWING LEGEND

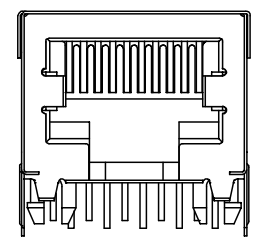
- SHEET 1- NOTES, DRAWING LEGEND
- SHEET 2- SHIELDED MODULAR JACK W/ BOTTOM GROUND TABS
- SHEET 3- SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS
- SHEET 4- UNSHIELDED MODULAR JACK
- SHEET 5- PART NUMBER CHARTS
- SHEET 6- PART NUMBER CHARTS
- SHEET 7- FOOTPRINT LAYOUT FOR 4 POSITION HOUSING
- SHEET 8- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING
- SHEET 9- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING

OBS COLORED JACKS EC NO: UCP2008-1189 DRAWN:JBELL 2007/11/30 CHKD:LSCHMIDT 2008/02/20 APPR:FSM/TH 2008/03/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▼=0 ▽=0	mm INCH	IN/MM	4:1	INCH		
		4 PLACES ±--- ±--- 3 PLACES ±--- ±.010 2 PLACES ±0.25 ±.014 1 PLACE ±0.36 ±---	DRAWN BY DATE JTR 1993/03/31	TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY			
		ANGULAR ±1/2°	CHECKED BY DATE JTR 1993/03/31	MOLEX INCORPORATED			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY DATE RAS 1993/03/31	MATERIAL NO.	DOCUMENT NO.	SHEET NO. 1 OF 9		
L4	REV	SEE SHTS 5&6 SDA-43202					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

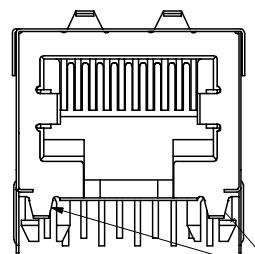
SHIELDED MODULAR JACK W/BOTTOM GROUND TABS

SIZE 8 LOADED 10 VERSION SHOWN

SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



OPTION "A"
NO TOP OR SIDE TABS

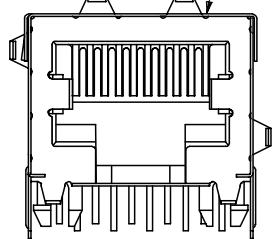


OPTION "B"
TOP TABS

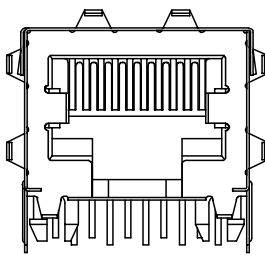
BOTTOM
GROUND TABS

OPTIONAL TOP GROUND TABS

SHIELDED MODULAR JACK ASSEMBLY
SEE SHEET 5 FOR MATERIAL NO.

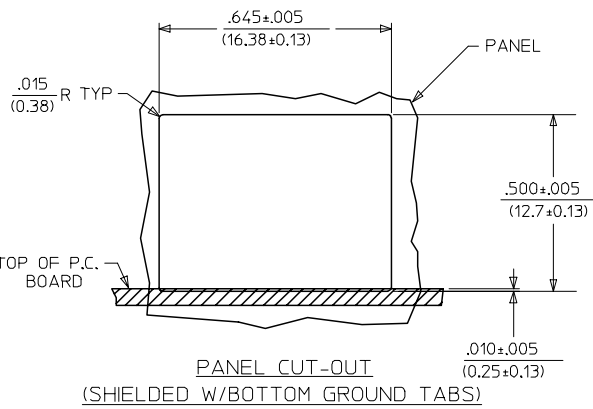
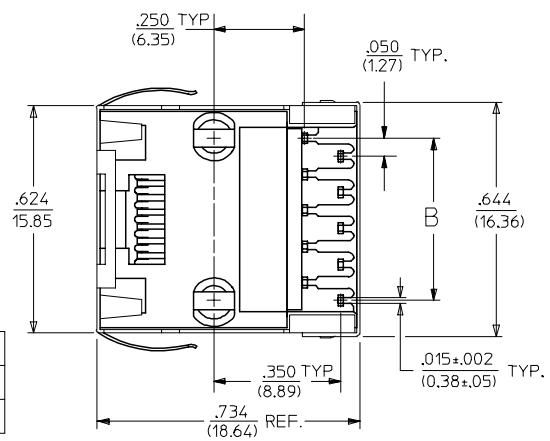
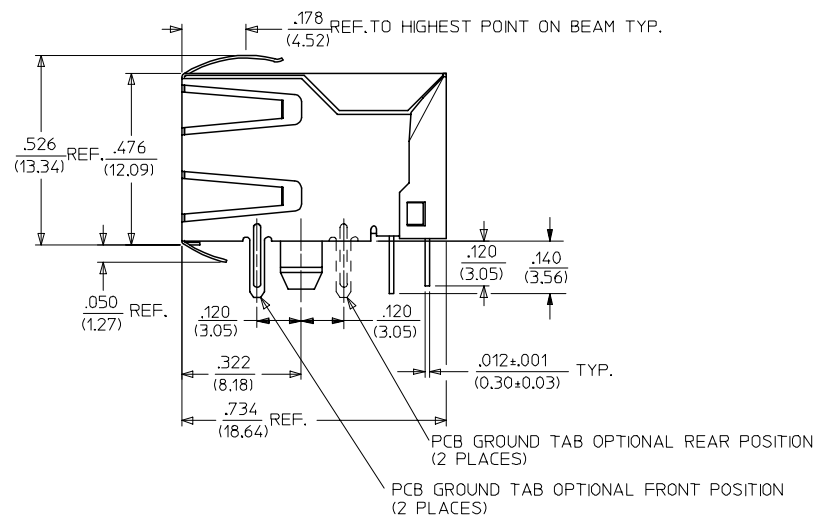


OPTION "C"
TOP AND STAGGERED SIDE TABS



OPTION "D"
TOP AND SIDE TABS

OPTIONAL SIDE
GROUND TABS
(2 PLACES)



HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450±.005 11.43±.13
8	8	.350±.005 8.89±.13

SEE SHEET ONE FC NO: UCP2004-1888 DRWN: LSCHMIDT 2004/03/31 CHKD: LSCHMIDT 2004/03/31 APPR: FSMITH 2004/03/31 L1	QUALITY SYMBOLS ▽ - 0 ▽ - 0	GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ±1/2°	SCALE 4:1 DIMENSION STYLE IN/MM	DESIGN UNITS INCH DRAWN BY JTR DATE 1993/03/31 CHECKED BY JTR DATE 1993/03/31 APPROVED BY RAS DATE 1993/03/31	THIRD ANGLE PROJECTION REVISE ON CAD ONLY	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY mox MOLEX INCORPORATED	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		MATERIAL NO. SEE SHT 5 DOCUMENT NO. SDA-43202 SHEET NO. 2 OF 9	
		MOLEX INCORPORATED					
		MOLEX INCORPORATED					

SHIELDED MODULAR JACKS W/BOTTOM GROUND TABS (SHEET 2)

ASSEMBLY MATERIAL NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	TERMINAL PLATING OPTION	PACKAGING OPTION	HOUSING COLOR
43202-8900	8	10	A	FRONT POSITION	A	TRAY	BLACK
43202-8901	8	10	B	FRONT POSITION	A	TRAY	
43202-8902	8	10	C	FRONT POSITION	A	TRAY	
43202-8903	8	10	D	FRONT POSITION	A	TRAY	
43202-8908	8	10	A	REAR POSITION	A	TRAY	
43202-8909	8	10	B	REAR POSITION	A	TRAY	
43202-8910	8	10	C	REAR POSITION	A	TRAY	
43202-8911	8	10	D	REAR POSITION	A	TRAY	
43202-8916	8	8	A	FRONT POSITION	A	TRAY	
43202-8917	8	8	B	FRONT POSITION	A	TRAY	
43202-8918	8	8	C	FRONT POSITION	A	TRAY	
43202-8919	8	8	D	FRONT POSITION	A	TRAY	
43202-8924	8	8	A	REAR POSITION	A	TRAY	
43202-8925	8	8	B	REAR POSITION	A	TRAY	
43202-8926	8	8	C	REAR POSITION	A	TRAY	
43202-8927	8	8	D	REAR POSITION	A	TRAY	

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SEE SHEET 1 EC NO: UCP2004-1347 DRWN:MKANARAO004/02/09 CHKD:MKANARAO004/02/09 APPR:BMWKUS 2004/02/10 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
		mm INCH	DIMENSION STYLE IN/MM	TITLE		
		4 PLACES ± --- ± ---	DRAWN BY DATE	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY		
		3 PLACES ± --- ±.010	JTR 1993/03/18			
2 PLACES ± 0.25 ±.014	CHECKED BY DATE	MOLEX INCORPORATED				
1 PLACE ± 0.36 ± ---	JTR 1993/03/18	APPROVED BY DATE MATERIAL NO. DOCUMENT NO. SHEET NO. RAS 1993/03/18 SEE CHART SDA-43202 5 OF 9				
	ANGULAR ±1/2°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(10 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(8 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(6 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

ADD PCB THICKNESS EC NO: UCP2005-2739 DRWN: L.SCHMIDT 2005/06/20 CHKD: ELHAG 2005/06/22 APPR: F.SMITH 2005/06/23 REV: L2	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	-0 -0	mm	INCH	DIMENSION STYLE IN/MM		TITLE		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	DRAWN BY L.E.LENZ	DATE 1995/03/09	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY		
		2 PLACES ± 0.25 ± .014	1 PLACE ± 0.36 ± ---	CHECKED BY JTR	DATE 1995/03/09			
ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY RAS	DATE 1995/03/09	MATERIAL NO. SEE SHTS 5&6	DOCUMENT NO. SDA-43202	SHEET NO. 9 OF 9	
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